



PMEG6002EJ-Q

200 mA low Vf MEGA Schottky barrier rectifier

3 May 2022

Product data sheet

1. General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in an SOD323F (SC-90) very small and flat lead Surface-Mounted Device (SMD) plastic package.

2. Features and benefits

- Average forward current: $I_{F(AV)} \leq 0.2 \text{ A}$
- Reverse voltage: $V_R \leq 60 \text{ V}$
- Low forward voltage
- Small and flat lead SMD plastic package
- Qualified according to AEC-Q101 and recommended for use in automotive applications

3. Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch Mode Power Supply (SMPS)
- Reverse polarity protection
- Ultra high-speed switching
- Low power consumption applications

4. Quick reference data



Table 1. Quick reference data

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-------------|-------------------------|--|-----|-----|-----|---------------|
| $I_{F(AV)}$ | average forward current | square-wave pulse; $\delta = 0.5$; $f = 20 \text{ kHz}$; $T_{amb} \leq 130 \text{ }^\circ\text{C}$ [1] | - | - | 0.2 | A |
| | | square-wave pulse; $\delta = 0.5$; $f = 20 \text{ kHz}$; $T_{sp} \leq 145 \text{ }^\circ\text{C}$ | - | - | 0.2 | A |
| V_R | reverse voltage | $T_j = 25 \text{ }^\circ\text{C}$ | - | - | 60 | V |
| V_F | forward voltage | $I_F = 200 \text{ mA}$; $T_j = 25 \text{ }^\circ\text{C}$ | - | 540 | 600 | mV |
| I_R | reverse current | $V_R = 60 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$ | - | 20 | 100 | μA |

[1] Device mounted on a ceramic PCB, Al_2O_3 , standard footprint.

5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description | Simplified outline | Graphic symbol |
|-----|--------|-------------|--|---|
| 1 | K | cathode |  SC-90 (SOD323F) |  sym001 |
| 2 | A | anode | | |

6. Ordering information

Table 3. Ordering information

| Type number | Package | | |
|------------------------------|---------|---|-------------------------|
| | Name | Description | Version |
| PMEG6002EJ-Q | SC-90 | plastic, surface-mounted package; 2 leads; 1.7 mm x 1.25 mm x 0.7 mm body | SOD323F |

7. Marking

Table 4. Marking codes

| Type number | Marking code |
|--------------|--------------|
| PMEG6002EJ-Q | 1P |

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | | Min | Max | Unit |
|-------------|-------------------------------------|---|---------|-----|-------|------|
| V_R | reverse voltage | $T_j = 25\text{ °C}$ | | - | 60 | V |
| $I_{F(AV)}$ | average forward current | square-wave pulse; $\delta = 0.5$; $f = 20\text{ kHz}$; $T_{amb} \leq 130\text{ °C}$ | [1] | - | 0.2 | A |
| | | square-wave pulse; $\delta = 0.5$; $f = 20\text{ kHz}$; $T_{sp} \leq 145\text{ °C}$ | | - | 0.2 | A |
| I_{FRM} | repetitive peak forward current | $t_p \leq 1\text{ ms}$; $\delta \leq 0.25$ | | - | 2.6 | A |
| I_{FSM} | non-repetitive peak forward current | square-wave pulse; $t_p = 8\text{ ms}$ | [2] | - | 2.75 | A |
| P_{tot} | total power dissipation | $T_{amb} \leq 25\text{ °C}$ | [3] [4] | - | 385 | mW |
| | | | [3] [5] | - | 695 | mW |
| | | | [3] [1] | - | 1.045 | W |
| T_j | junction temperature | | | - | 150 | °C |
| T_{amb} | ambient temperature | | | -55 | 150 | °C |
| T_{stg} | storage temperature | | | -65 | 150 | °C |

[1] Device mounted on a ceramic PCB, Al_2O_3 , standard footprint.

[2] $T_j = 25\text{ °C}$ prior to surge.

[3] Reflow soldering is the only recommended soldering method.

[4] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

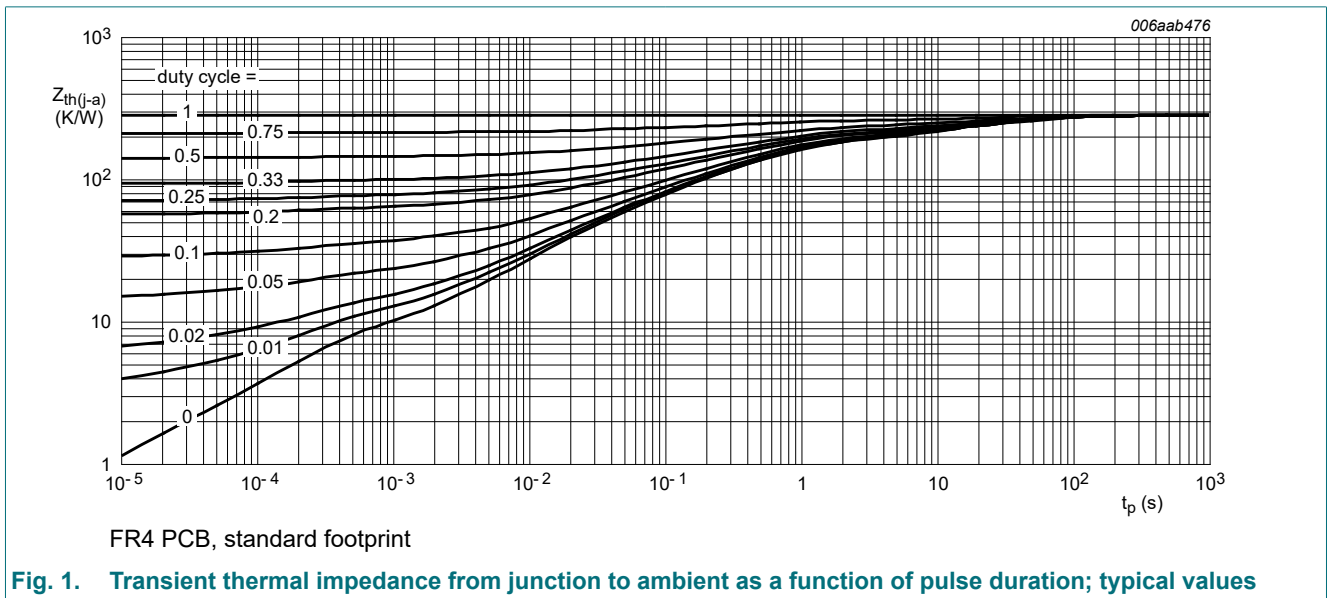
[5] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm^2 .

9. Thermal characteristics

Table 6. Thermal characteristics

| Symbol | Parameter | Conditions | | Min | Typ | Max | Unit |
|----------------|--|-------------|-------------|-----|-----|-----|------|
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | in free air | [1] [2] [3] | - | - | 325 | K/W |
| | | | [1] [2] [4] | - | - | 180 | K/W |
| | | | [1] [2] [5] | - | - | 120 | K/W |
| $R_{th(j-sp)}$ | thermal resistance from junction to solder point | | [6] | - | - | 25 | K/W |

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.
- [2] Reflow soldering is the only recommended soldering method.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².
- [5] Device mounted on a ceramic PCB, Al₂O₃, standard footprint.
- [6] Soldering point of cathode tab.



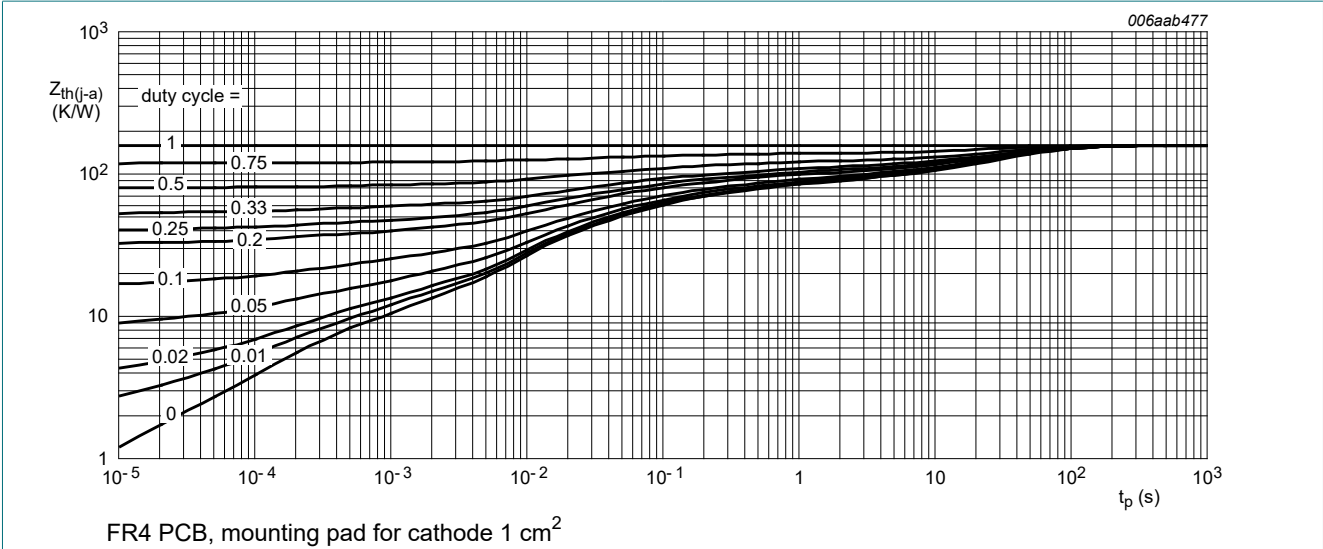


Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

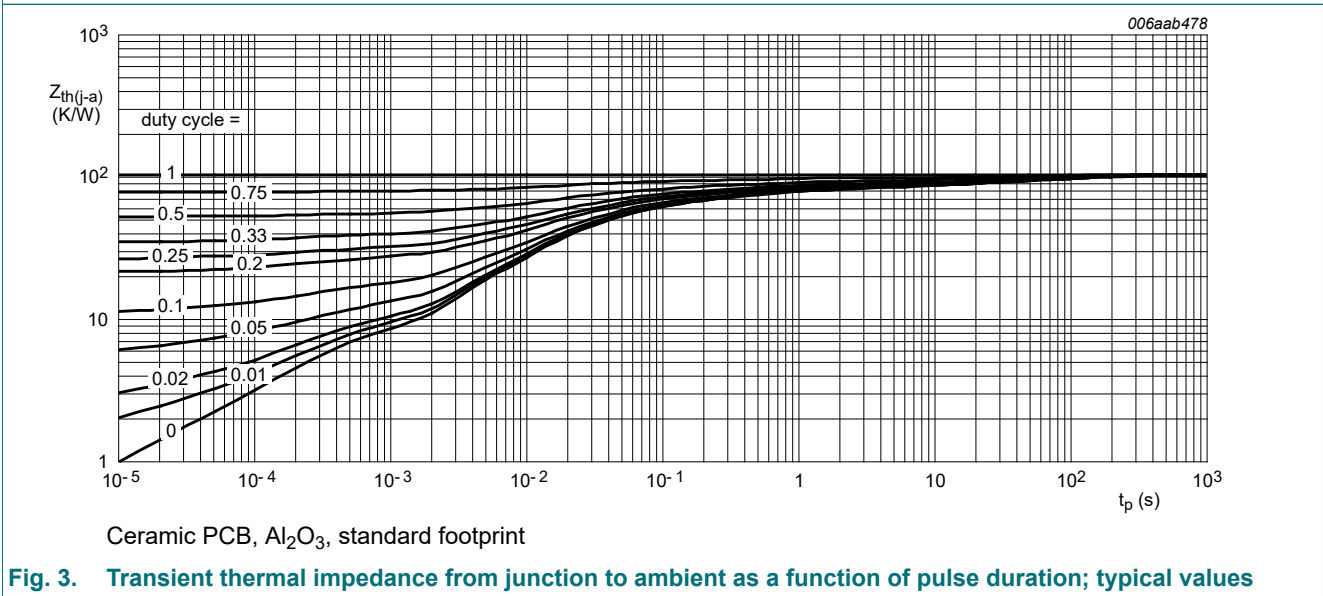
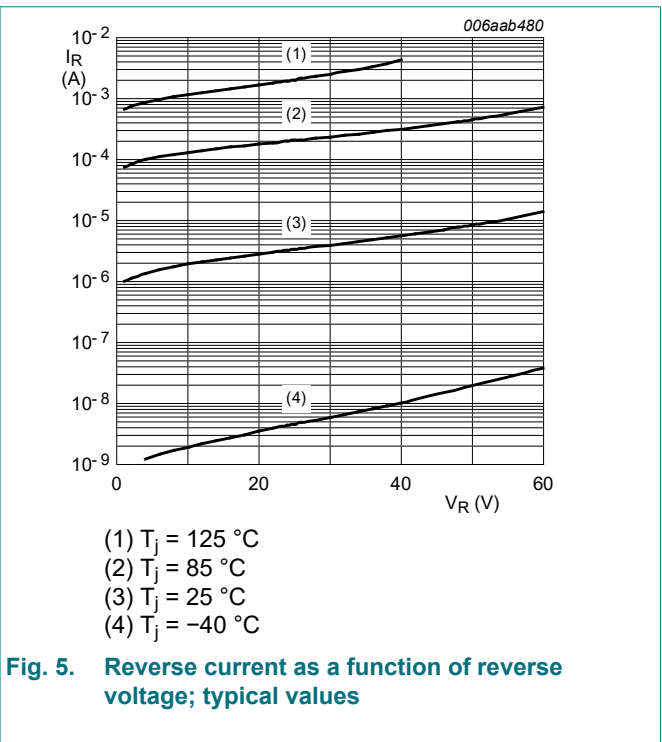
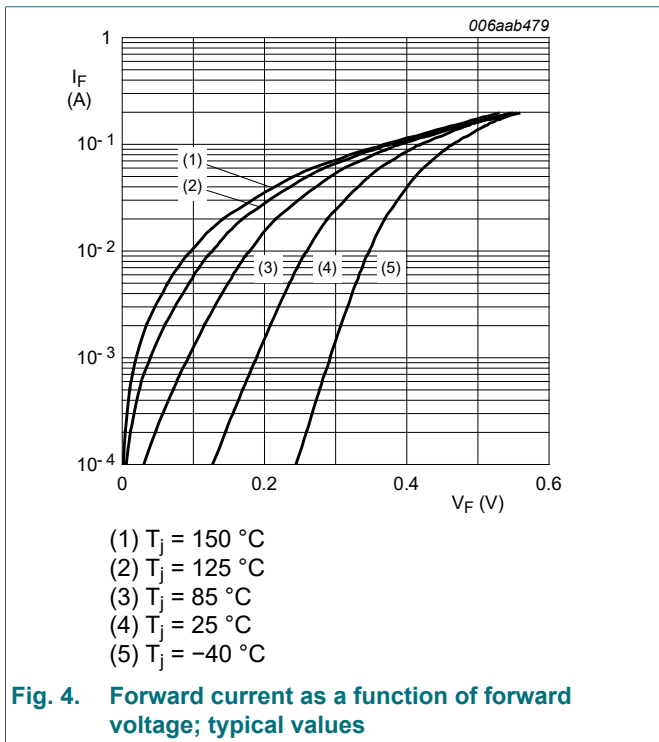


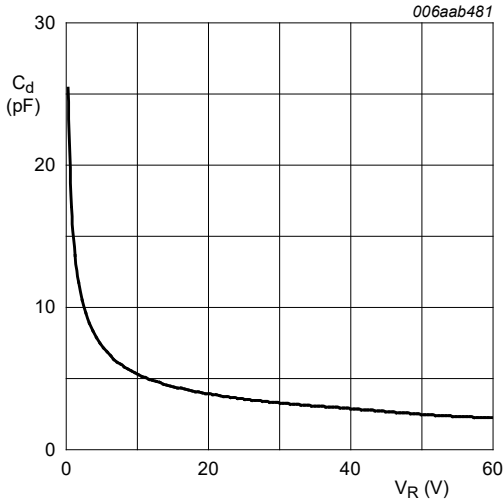
Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

Table 7. Characteristics

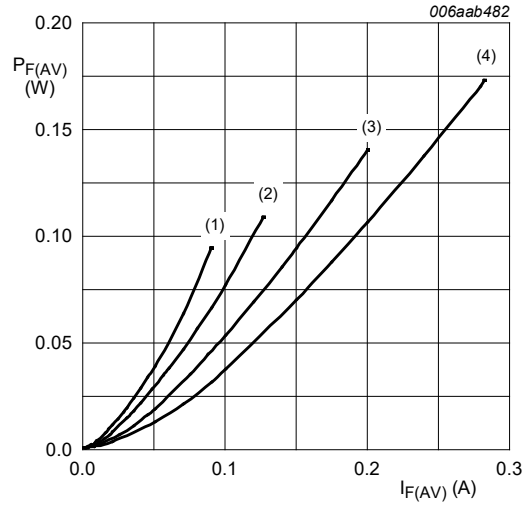
| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|----------|-----------------------|---|-----|-----|-----|---------------|
| V_F | forward voltage | $I_F = 0.1 \text{ mA}; T_j = 25 \text{ }^\circ\text{C}$ | - | 130 | 170 | mV |
| | | $I_F = 1 \text{ mA}; T_j = 25 \text{ }^\circ\text{C}$ | - | 190 | 230 | mV |
| | | $I_F = 10 \text{ mA}; T_j = 25 \text{ }^\circ\text{C}$ | - | 260 | 300 | mV |
| | | $I_F = 100 \text{ mA}; T_j = 25 \text{ }^\circ\text{C}$ | - | 420 | 470 | mV |
| | | $I_F = 200 \text{ mA}; T_j = 25 \text{ }^\circ\text{C}$ | - | 540 | 600 | mV |
| I_R | reverse current | $V_R = 10 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$ | - | 2 | 10 | μA |
| | | $V_R = 50 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$ | - | 9 | 30 | μA |
| | | $V_R = 60 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$ | - | 20 | 100 | μA |
| C_d | diode capacitance | $V_R = 1 \text{ V}; f = 1 \text{ MHz}; T_j = 25 \text{ }^\circ\text{C}$ | - | 14 | - | pF |
| | | $V_R = 10 \text{ V}; f = 1 \text{ MHz}; T_j = 25 \text{ }^\circ\text{C}$ | - | 6 | - | pF |
| t_{rr} | reverse recovery time | $T_j = 25 \text{ }^\circ\text{C}$; When switched from $I_F = 10 \text{ mA}$ to $I_R = 10 \text{ mA}$; $R_L = 100 \text{ }\Omega$; measured at $I_R = 1 \text{ mA}$. | - | 5 | - | ns |





$f = 1 \text{ MHz}; T_{\text{amb}} = 25 \text{ }^\circ\text{C}$

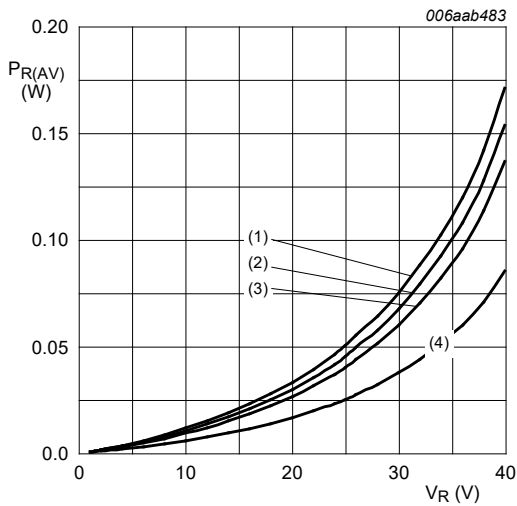
Fig. 6. Diode capacitance as a function of reverse voltage; typical values



$T_j = 150 \text{ }^\circ\text{C}$

- (1) $\delta = 0.1$
- (2) $\delta = 0.2$
- (3) $\delta = 0.5$
- (4) $\delta = 1$

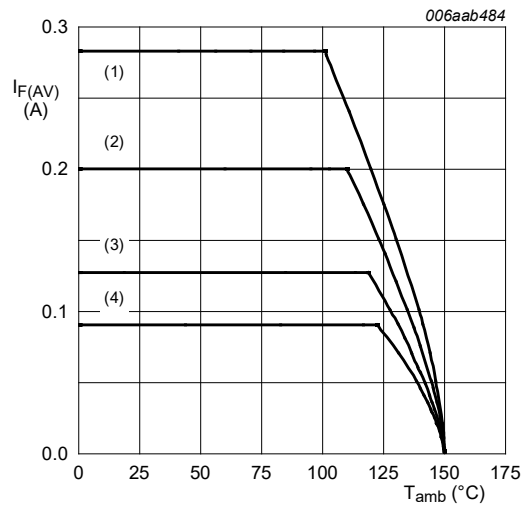
Fig. 7. Average forward power dissipation as a function of average forward current; typical values



$T_j = 125 \text{ }^\circ\text{C}$

- (1) $\delta = 1$
- (2) $\delta = 0.9$
- (3) $\delta = 0.8$
- (4) $\delta = 0.5$

Fig. 8. Average reverse power dissipation as a function of reverse voltage; typical values

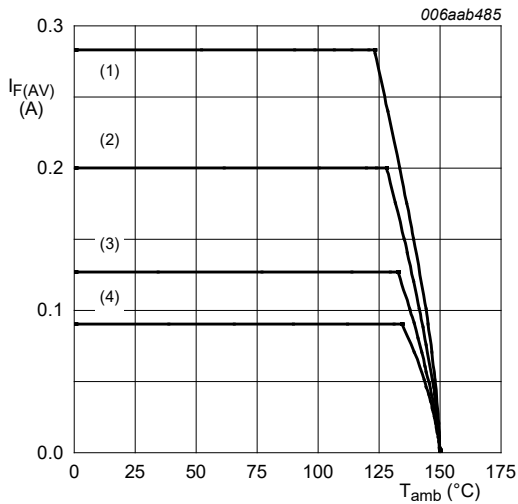


FR4 PCB, standard footprint

$T_j = 150 \text{ }^\circ\text{C}$

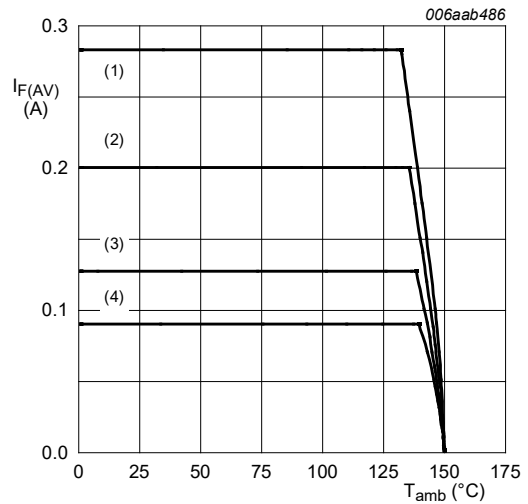
- (1) $\delta = 1$ (DC)
- (2) $\delta = 0.5; f = 20 \text{ kHz}$
- (3) $\delta = 0.2; f = 20 \text{ kHz}$
- (4) $\delta = 0.1; f = 20 \text{ kHz}$

Fig. 9. Average forward current as a function of ambient temperature; typical values



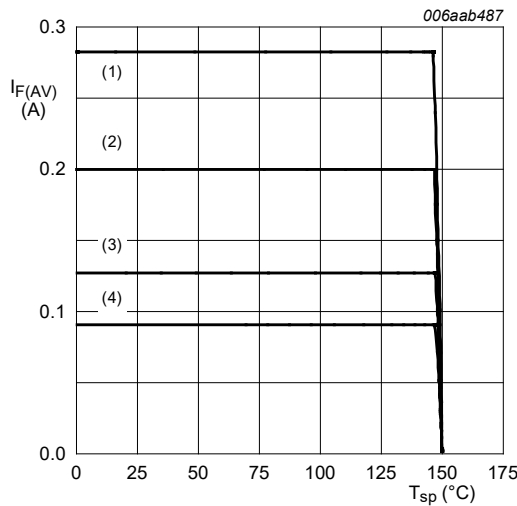
FR4 PCB, mounting pad for cathode 1 cm²
 $T_j = 150\text{ °C}$
 (1) $\delta = 1$ (DC)
 (2) $\delta = 0.5$; $f = 20\text{ kHz}$
 (3) $\delta = 0.2$; $f = 20\text{ kHz}$
 (4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig. 10. Average forward current as a function of ambient temperature; typical values



Ceramic PCB, Al₂O₃, standard footprint
 $T_j = 150\text{ °C}$
 (1) $\delta = 1$ (DC)
 (2) $\delta = 0.5$; $f = 20\text{ kHz}$
 (3) $\delta = 0.2$; $f = 20\text{ kHz}$
 (4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig. 11. Average forward current as a function of ambient temperature; typical values



$T_j = 150\text{ °C}$
 (1) $\delta = 1$ (DC)
 (2) $\delta = 0.5$; $f = 20\text{ kHz}$
 (3) $\delta = 0.2$; $f = 20\text{ kHz}$
 (4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig. 12. Average forward current as a function of solder point temperature; typical values

11. Test information

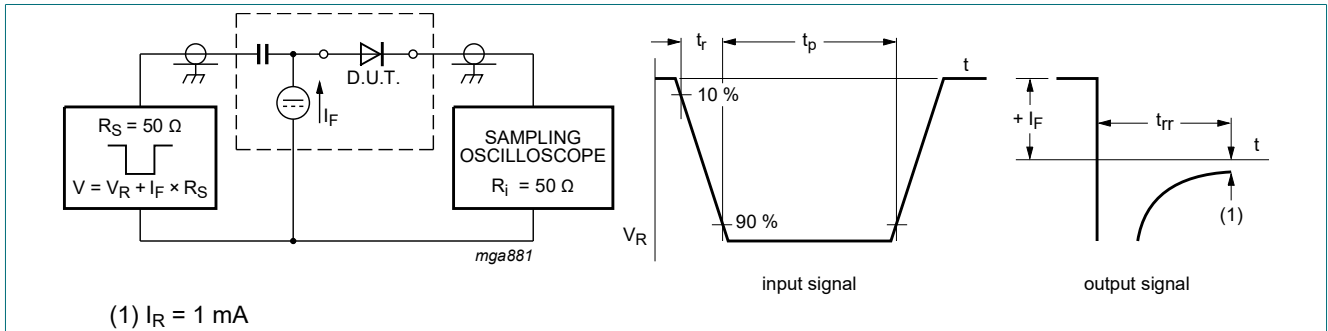


Fig. 13. Reverse recovery time: test circuit and waveforms

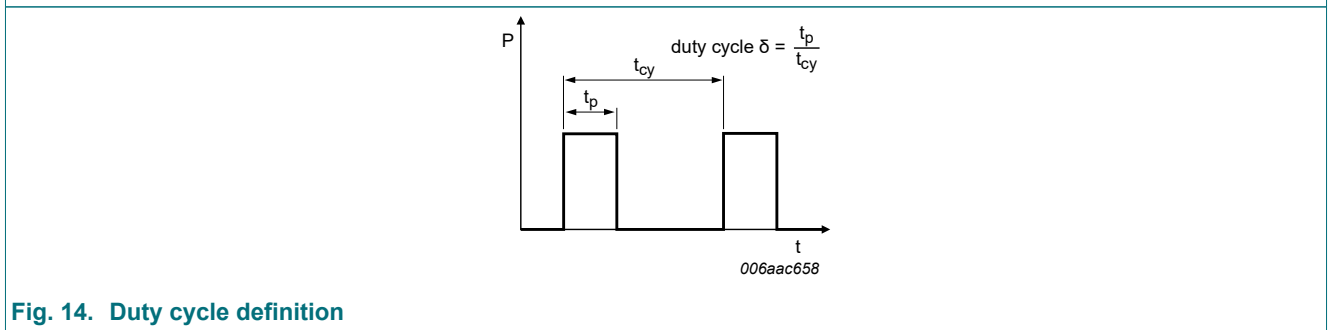


Fig. 14. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations: $I_{F(AV)} = I_M \times \delta$ with I_M defined as peak current, $I_{RMS} = I_{F(AV)}$ at DC, and $I_{RMS} = I_M \times \sqrt{\delta}$ with I_{RMS} defined as RMS current.

Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

12. Package outline

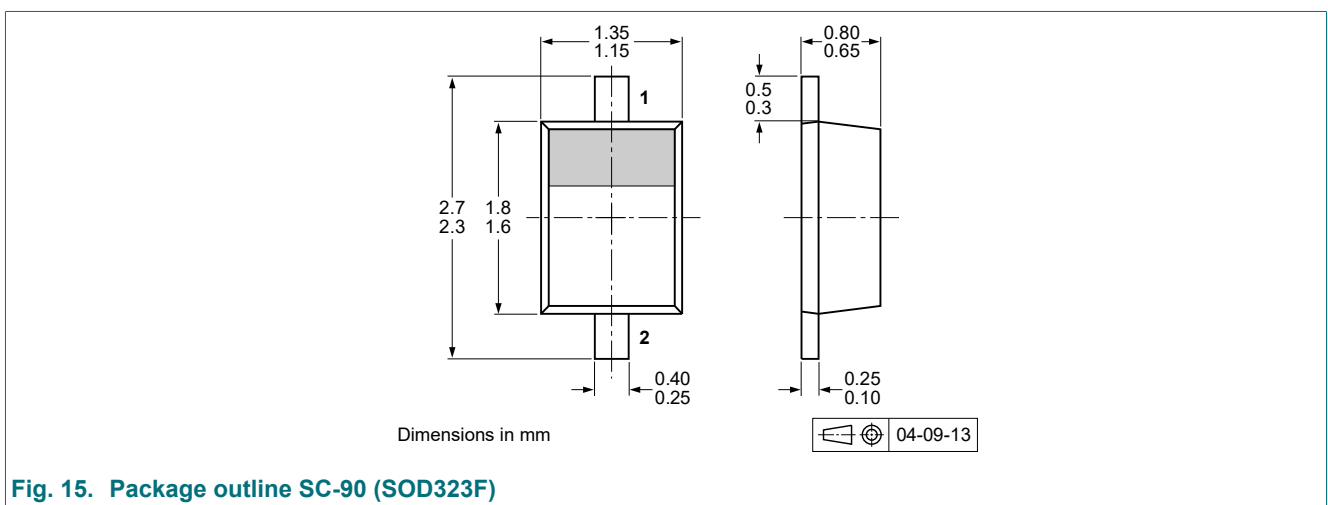


Fig. 15. Package outline SC-90 (SOD323F)

13. Soldering

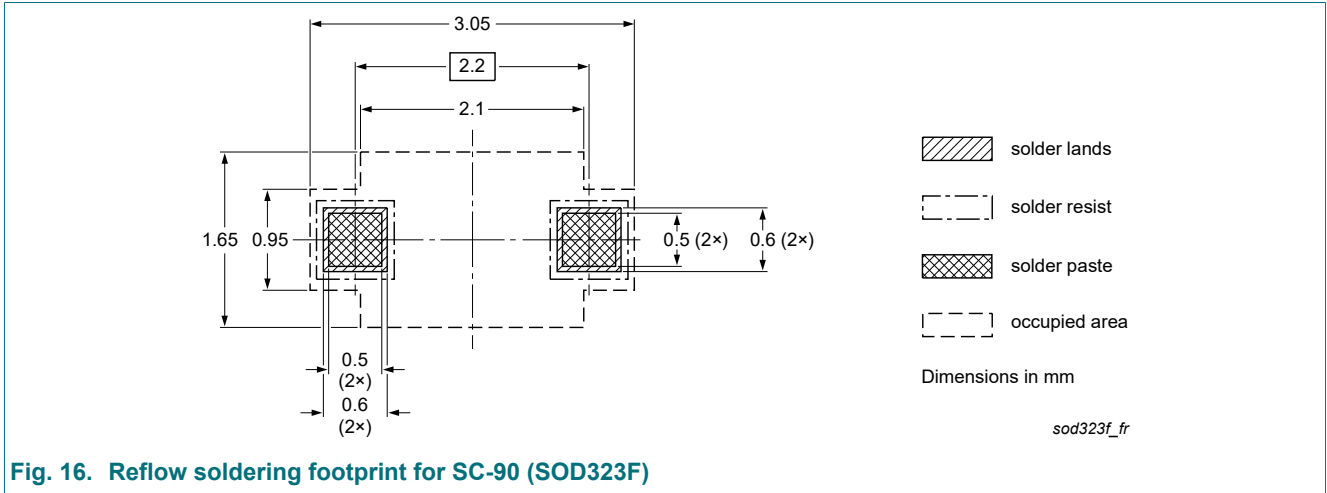


Fig. 16. Reflow soldering footprint for SC-90 (SOD323F)

14. Revision history

Table 8. Revision history

| Data sheet ID | Release date | Data sheet status | Change notice | Supersedes |
|------------------|--------------|--------------------|---------------|------------|
| PMEG6002EJ-Q v.1 | 20220503 | Product data sheet | - | - |

15. Legal information

Data sheet status

| Document status [1][2] | Product status [3] | Definition |
|--------------------------------|--------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
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